



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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TG-LH-EE-90-5

Electronics Epoxy

Description

TG-LH-EE-90-5 is a one-part white adhesive based on epoxy resins. It cures fast at elevated temperatures and has excellent adhesion to most pc boards and electronic components. It may be cured at 100°C or faster at 175°C. It has no sagging. It has a stable pot life and long shelf life even at room temperature of 25°C. It has been designed especially for bonding electronic components. It has relatively low viscosity for faster dispense from syringes. It has high thixotropic which can control the flow of the adhesive.

Applications

Epoxy adhesive for attaching to ceramic, metals, and most plastics in electronics

Guidelines for Use

1. Thaw the epoxy to room temperature (25 °C) before use
2. Dispense the epoxy by using a syringe
3. Wipe off any excess uncured adhesive with a piece of dry cloth or tissue. Further cleaning may be achieved with tissue dabbed with iso-propanol-alcohol (IPA)
4. Cure the epoxy by heating at 100 °C for 120 minutes in a convection oven. Curing at lower temperature will require a longtime

Properties

- REACH Compliant
- ROHS Compliant

Property	TG-LH-EE-90	Unit	Test Method
Chemical type	Epoxy	-	-
Appearance	White paste	-	Visual
Mix ratio, by weight	One component	-	-
Shelf life, 2°C	6	Month	ASTM F2914
Pot life, 25°C	1	Week	ASTM F2914
Viscosity, CAP 2000+ viscometer, 25°C Cap-06@40rpm	24,000	cps	ASTM D1084
Thixotropic Index	1.8	-	-
Hardness, cured 100°C for 2 hr	90	Shore D	ASTM D2240
Shear Strength	545	kgcm ⁻²	ASTM D412
Water boil, wt gain, 100°C/1hr	0.35	%	-
Tg, DSC, cured 100°C for 2 hr	122	°C	-
Specific gravity	1.20	g/cm ³	ASTM D792
CTE, alpha-1	6.2 x 10 ⁻⁵	mm ⁻¹ °C ⁻¹	-
, alpha-2	1.8 x 10 ⁻⁴	mm ⁻¹ °C ⁻¹	-
Ionic Content, Cl	<50	ppm	-
, K	<50	ppm	-
, Na	<20	ppm	-

Packaging

5 ml EFD syringe
 10 ml EFD syringe
 30 ml EFD syringe

Recommended Cure

Temp. (°C)	Gel time	Cure time
100	12 mins	2 hrs
150	2 mins	30 mins

Storage

Store in fridge at 2°C. Tightly close original container of unused product. Storing at lower temperatures down to -20°C may prolong shelf life beyond 6 months. However it may take longer time to thaw the product

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